



**THE DATASHEET OF
SPHWAHDF25YZT2D1**



High Voltage LED Series Chip on Board

LC019D – Gen.1



High efficacy COB LED package
well-suited for use in spotlight applications

Features & Benefits

- Chip on Board (COB) solution makes it easy to design in
- Simple assembly reduces manufacturing cost
- Low thermal resistance
- InGaN/GaN MQW LED with long time reliability

Applications

- Spotlight / Downlight
- LED Retrofit Bulbs
- Outdoor Illumination



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1. Characteristics

a) Absolute Maximum Rating

Item	Symbol	Rating	Unit	Condition
Ambient / Operating Temperature	T_a	-40 ~ +105	°C	-
Storage Temperature	T_{stg}	-40 ~ +120	°C	-
LED Junction Temperature	T_J	140	°C	-
Case Temperature	T_c	105	°C	-
Forward Current	I_F	1380	mA	-
Power Dissipation	P_D	51.8	W	-
ESD (HBM)	-	±2	kV	-
ESD (MM)	-	±0.5	kV	-

b) Electro-optical Characteristics ($I_F = 540 \text{ mA}$, $T_J = 85 \text{ °C}$)

Item	Unit	Rank	Min.	Typ.	Max.
Forward Voltage (V_F)	V	YZ	31.8	34.6	37.5
Color Rendering Index (R_a)	-	5	80	-	-
		7	90	-	-
Thermal Resistance (junction to chip point)	°C/W		-	1.0	-
Beam Angle	°		-	115	-
Nominal Power	W			20.3	

Notes:

- 1) The COB is tested in pulsed condition at rated test current (10 ms pulse width) and rated temperature ($T_J = T_C = T_a = 85 \text{ °C}$)
- 2) Samsung maintains measurement tolerance of: forward voltage = ±5 %, CRI = ±1
- 3) Refer to the derating curve, '3. Typical Characteristics Graph' designed within the range.

c) Luminous Flux Characteristics ($I_F = 540 \text{ mA}$)

CRI (R_a) Min.	Nominal CCT (K)	Flux Rank	Flux @ $T_J = 85 \text{ }^\circ\text{C}$ (lm)		
			Min.	Typ.	Max.
80	2700	J3	2335	2458	-
		D1	2458	2581	-
	3000	J4	2462	2592	-
		D1	2592	2722	-
	3500	J5	2538	2672	-
		D1	2672	2805	-
	4000	J5	2590	2726	-
		D1	2726	2863	-
	5000	J6	2618	2756	-
		D1	2756	2894	-
	5700	J6	2618	2756	-
		D1	2756	2894	-
	6500	J5	2590	2726	-
		D1	2726	2863	-

CRI (R_a) Min.	Nominal CCT (K)	Flux Rank	Flux @ $T_J = 85 \text{ }^\circ\text{C}$ (lm)		
			Min.	Typ.	Max.
90	2700	H9	1999	2104	-
		D1	2104	2210	-
	3000	J0	2096	2207	-
		D1	2207	2317	-
	3500	J1	2173	2287	-
		D1	2287	2402	-
	4000	J2	2220	2337	-
		D1	2337	2454	-
	5000	J2	2222	2339	-
		D1	2339	2456	-

Notes:

- 1) The COB is tested in pulsed operating condition at rated test current (10 ms pulse width) and rated temperature ($T_J = T_C = 85 \text{ }^\circ\text{C}$).
- 2) Samsung maintains measurement tolerance of: Luminous flux = $\pm 7 \%$, CRI = ± 1

2. Product Code Information

1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18
S	P	H	W	H	A	H	D	N	F	2	5	Y	Z	W	3	J	3

Digit	PKG Information	Code	Specification
1 2 3	Samsung Package High Power	SPH	
4 5	Color	WH	White
6	Product Version	A	
7 8	Form Factor	HD	COB
9	Lens Type	N	No lens
10	Wattage or Model	F	LC019D
11	Internal Code	2	
12	CRI & Sorting Temperature	5 7	Min. 80 (85°C) Min. 90 (85°C)
13 14	Forward Voltage (V)	YZ	31.8~37.5
15	CCT (K)	W V U T R Q P	2700K 3000K 3500K 4000K 5000K 5700K 6500K
16	MacAdam Step	2 3	MacAdam 2-step MacAdam 3-step
17 18	Luminous Flux	H9 J0 J1 J2 J3 J4 J5 J6	Min. 1900 Min. 2000 Min. 2100 Min. 2200 Min. 2300 Min. 2400 Min. 2500 Min. 2600

a) Binning Structure ($I_F = 540 \text{ mA}$, $T_J = 85 \text{ }^\circ\text{C}$)

CRI (R_a) Min.	Nominal CCT (K)	Product Code	V_F Rank	Color Rank	Flux Rank	Flux Range (Φ_v , lm)
80	2700	SPHWAHDFNF25YZW2J3	YZ	W2	J3	2335 ~
		SPHWAHDFNF25YZW3J3		W3		
		SPHWAHDFNF25YZW2D1		W2	D1	
		SPHWAHDFNF25YZW3D1		W3		
	3000	SPHWAHDFNF25YZV24	YZ	V2	J4	2462 ~
		SPHWAHDFNF25YZV3J4		V3		
		SPHWAHDFNF25YZV2D1		V2	D1	
		SPHWAHDFNF25YZV3D1		V3		
	3500	SPHWAHDFNF25YZU25	YZ	U2	J5	2538 ~
		SPHWAHDFNF25YZU3J5		U3		
		SPHWAHDFNF25YZU2D1		U2	D1	
		SPHWAHDFNF25YZU3D1		U3		
	4000	SPHWAHDFNF25YZT25	YZ	T2	J5	2590 ~
		SPHWAHDFNF25YZT3J5		T3		
		SPHWAHDFNF25YZT2D1		T2	D1	
		SPHWAHDFNF25YZT3D1		T3		
	5000	SPHWAHDFNF25YZR3J6	YZ	R3	J6	2618 ~
		SPHWAHDFNF25YZR3D1			D1	2756 ~
	5700	SPHWAHDFNF25YZQ3J6	YZ	Q3	J6	2618 ~
		SPHWAHDFNF25YZQ3D1			D1	2756 ~
6500	SPHWAHDFNF25YZP3J5	YZ	P3	J5	2590 ~	
	SPHWAHDFNF25YZP3D1			D1	2726 ~	

CRI (R _a) Min.	Nominal CCT (K)	Product Code	V _F Rank	Color Rank	Flux Rank	Flux Range (Φ _v , lm)
90	2700	SPHWHAHDNF27YZW2H9	YZ	W2	H9	1999 ~
		SPHWHAHDNF27YZW3H9		W2		
		SPHWHAHDNF27YZW2D1		W2	D1	2104 ~
		SPHWHAHDNF27YZW3D1		W2		
	3000	SPHWHAHDNF27YZV2J0	YZ	V2	J0	2096 ~
		SPHWHAHDNF27YZV3J0		V3		
		SPHWHAHDNF27YZV2D1		V2	D1	2207 ~
		SPHWHAHDNF27YZV3D1		V3		
	3500	SPHWHAHDNF27YZU2J1	YZ	U2	J1	2173 ~
		SPHWHAHDNF27YZU3J1		U3		
		SPHWHAHDNF27YZU2D1		U2	D1	2287 ~
		SPHWHAHDNF27YZU3D1		U3		
	4000	SPHWHAHDNF27YZT2J2	YZ	T2	J2	2220 ~
		SPHWHAHDNF27YZT3J2		T3		
		SPHWHAHDNF27YZT2D1		T2	D1	2337 ~
		SPHWHAHDNF27YZT3D1		T3		
	5000	SPHWHAHDNG27YZR3J8	YZ	R3	J8	2222 ~
		SPHWHAHDNG27YZR3D1		R3	D1	2339 ~

b) Chromaticity Region & Coordinates ($I_F = 540 \text{ mA}$, $T_J = 85 \text{ }^\circ\text{C}$)

MacAdam Ellipse (W2, W3)					
Step	CIE x	CIE y	θ	a	b
2-step	0.4578	0.4101	53.70	0.0054	0.0028
3-step	0.4578	0.4101	53.70	0.0081	0.0042

MacAdam Ellipse (V2, V3)					
Step	CIE x	CIE y	θ	a	b
2-step	0.4338	0.403	53.22	0.0056	0.0027
3-step	0.4338	0.4030	53.22	0.0083	0.0041

MacAdam Ellipse (U2, U3)					
Step	CIE x	CIE y	θ	a	b
2-step	0.4073	0.3917	54.00	0.0062	0.0028
3-step	0.4073	0.3917	54.00	0.0093	0.0041

MacAdam Ellipse (T2, T3)					
Step	CIE x	CIE y	θ	a	b
2-step	0.3818	0.3797	53.72	0.0063	0.0027
3-step	0.3818	0.3797	53.72	0.0094	0.0040

MacAdam Ellipse (R3)					
Step	CIE x	CIE y	θ	a	b
3-step	0.3447	0.3553	59.62	0.0082	0.0035

MacAdam Ellipse (Q3)					
Step	CIE x	CIE y	θ	a	b
3-step	0.3287	0.3417	59.0950	0.0075	0.0032

MacAdam Ellipse (P3)					
Step	CIE x	CIE y	θ	a	b
3-step	0.3123	0.3282	58.5700	0.0067	0.0029

Note:

Samsung maintains measurement tolerance of: $C_x, C_y = \pm 0.005$

3. Typical Characteristics Graphs

a) Spectrum Distribution ($I_f = 540 \text{ mA}$, $T_J = 85 \text{ }^\circ\text{C}$)

CCT: 2700 K (80 CRI)



CCT: 3000 K (80 CRI)



CCT: 3500 K (80 CRI)



CCT: 4000 K (80 CRI)



CCT: 5000 K (80 CRI)



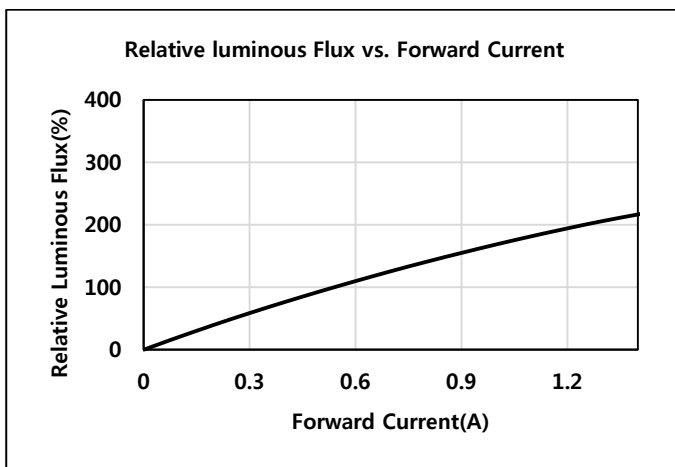
CCT: 5700 K (80 CRI)



CCT: 6500 K (80 CRI)



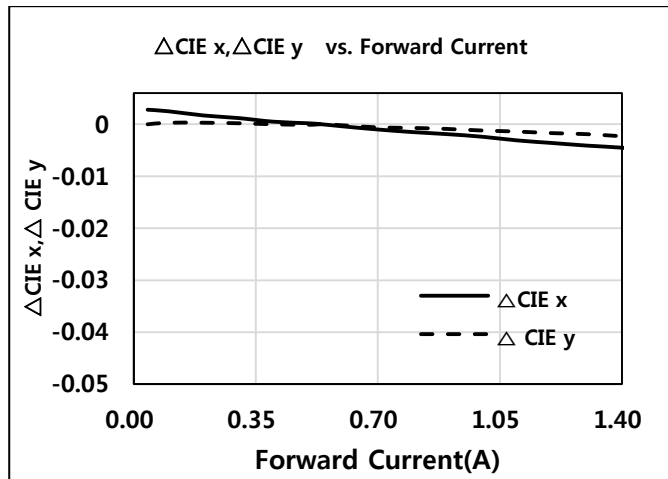
b) Forward Current Characteristics ($T_j = 85^\circ\text{C}$)



C) Temperature Characteristics ($I_f = 540\text{mA}$)



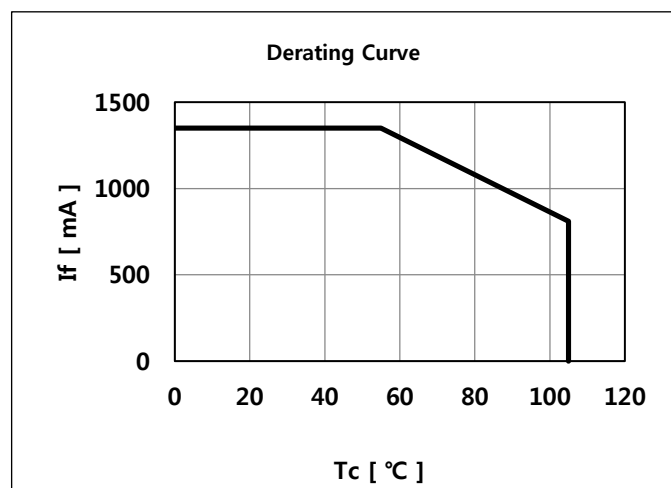
d) Color Shift Characteristics ($T_J = 85\text{ }^\circ\text{C}$, $I_F = 540\text{mA}$, CRI80+)



e) Beam Angle Characteristics ($I_F = 540\text{ mA}$, $T_J = 85\text{ }^\circ\text{C}$)



f) Derating Characteristics



4. Outline Drawing & Dimension



1. Unit: mm
2. Tolerance: ± 0.3 mm

Item	Dimension	Tolerance	Unit
Length	19.0	±0.15	mm
Width	19.0	±0.15	mm
Height	1.50	±0.30	mm
Light Emitting Surface (LES) Diameter	14.5	±0.30	mm

Note: Denoted product information above is only an example
 (LC019D18030 : LC019D, CRI80+, 3000K)

5. Reliability Test Items & Conditions

a) Test Items

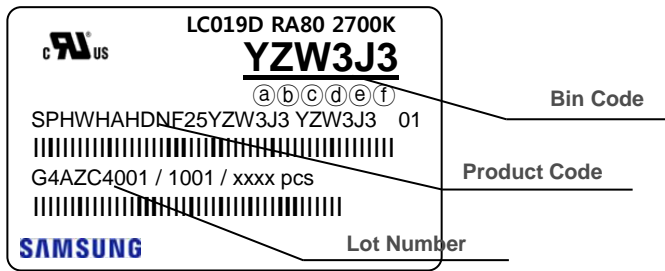
Test Item	Test Condition	Test Hour / Cycle
High Temperature Humidity Life Test	60 °C, 90 % RH., DC Derating, I_F	1000 h
High Temperature Life Test	85 °C, DC Derating, I_F	1000 h
Low Temperature Life Test	-40 °C, DC , $I_F = 970$ mA	1000 h
Pulsed Operating Life Test	55 °C, Pulse width 100 μ s, duty cycle 3 %	1000 h
High Temperature Storage	120 °C	1000 h
Low Temperature Storage	-40 °C	1000 h
Temperature Humidity Storage	60 °C, 90% RH	1000h
Temperature Cycle On/Off Test	-40 °C / 85 °C each 20 min, 30 min transfer power on/off each 5 min, DC Derating, $I_F = \text{max}$	100 cycles
ESD (HBM)	R ₁ : 10 M Ω R ₂ : 1.5 k Ω C: 100 pF V: ± 2 kV	5 times
ESD (MM)	R ₁ : 10 M Ω R ₂ : 0 k Ω C: 200 pF V: ± 0.2 kV	5 times
Vibration Test	20 ~ 80 Hz (displacement: 0.06 inch, max. 20 g) 80 ~ 2 kHz (max. 20 g) min. frequency \leftrightarrow max. frequency 4 min transfer	4 times
Mechanical Shock Test	1500 g, 0.5 ms each of the 6 surfaces (3 axis x 2 sides)	5 times
Sulfur Resistance	25 °C, 75%, H ₂ S 15 ppm	504h

b) Criteria for Judging the Damage

Item	Symbol	Test Condition ($T_c = 25$ °C)	Limit	
			Min.	Max.
Forward Voltage	V_F	$I_F = 540$ mA	L.S.L. * 0.9	U.S.L. * 1.1
Luminous Flux	Φ_v	$I_F = 540$ mA	L.S.L * 0.7	U.S.L * 1.3

6. Label Structure

a) Label Structure



Note: Denoted bin code and product code above is only an example (see description on page 5)

Bin Code:

- ⒶⒷ: Forward Voltage bin (refer to page 11)
- ⒸⒹ: Chromaticity bin (refer to page 9-10)
- ⒺⒻ: Luminous Flux bin (refer to page 6)

b) Lot Number

The lot number is composed of the following characters:



① ③④⑤⑥⑦⑧⑨ / 1ⒶⒷⒸ / xxxx pcs

- ① : Production site (S: Giheung, Korea, G: Tianjin, China)
- ② : 4 (LED)
- ③ : Product state (A: Normal, B: Bulk, C: First Production, R: Reproduction, S: Sample)
- ④ : Year (Z: 2015, A: 2016, B: 2017...)
- ⑤ : Month (1~9, A, B, C)
- ⑥⑦⑧⑨ : Day (1~9, A, B~V)
- ⒶⒷⒸ : Product serial number (001 ~ 999)

6. Packing Structure

Packing material	Max. quantity in pcs of COB	Dimension(mm)			
		Length	Width	Height	Tolerance
Tray	20	160	180	10	1.0
Aluminum Bag	40(2 trays)	210	241		10
Inner Box	160	230	84	260	2
Outer Box	1600	476	445	272	5

a) Packing Structure



b) Tray

① Cover

② Body



c) Aluminum Vinyl Packing Bag



8. Precautions in Handling & Use

- 1) This device should not be used in any type of fluid such as water, oil, organic solvent, etc. When cleaning is required, IPA is recommended as the cleaning agent. Some solvent-based cleaning agent may damage the silicone resins used in the device.
- 2) LEDs must be stored in a clean environment. If the LEDs are to be stored for three months or more after being shipped from Samsung, they should be packed with a nitrogen-filled container (shelf life of sealed bags is 12 months at temperature 0~40 °C, 0~90 % RH).
- 3) After storage bag is opened, device subjected to soldering, solder reflow, or other high temperature processes must be:
 - a. Mounted within 672 hours (28 days) at an assembly line with a condition of no more than 30 °C / 60 % RH, or
 - b. Stored at <10 % RH
- 4) Repack unused products with anti-moisture packing, fold to close any opening and then store in a dry place.
- 5) Devices require baking before mounting, if humidity card reading is >60 % at 23 ± 5 °C.
- 6) Devices must be baked for 1 hour at 60 ± 5 °C, if baking is required.
- 7) The LEDs are sensitive to the static electricity and surge current. It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs. If voltage exceeding the absolute maximum rating is applied to LEDs, it may cause damage or even destruction to LED devices. Damaged LEDs may show some unusual characteristics such as increase in leakage current, lowered turn-on voltage, or abnormal lighting of LEDs at low current.
- 8) The thermal management is one of the most critical factors for the LED lighting system. Especially the LED junction temperature should not exceed the absolute maximum rating while operation of LED lighting system.
For more information, please refer to Application Note 'Mechanical & Thermal Guide for COB'.
- 9) In case of driving LEDs around the minimum current level (I_{f_min}), chips might exhibit different brightness due to the variation in I-V characteristics of each one. This is normal and does not adversely affect the performance of product.
- 10) VOCs (Volatile Organic Compounds) can be generated from adhesives, flux, hardener or organic additives used in luminaires (fixtures). Transparent LED silicone encapsulant is permeable to those chemicals and they may lead to a discoloration of encapsulant when they exposed to heat or light. This phenomenon can cause a significant loss of light emitted (output) from the luminaires. In order to prevent these problems, we recommend users to know the physical properties of materials used in luminaires and they must be carefully selected.
- 11) The resin area is very sensitive, please do not handle, press, touch, rub, clean, or pick by with tweezers on it. Instead, please pick at the handling area as indicated below.



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